

Highlights

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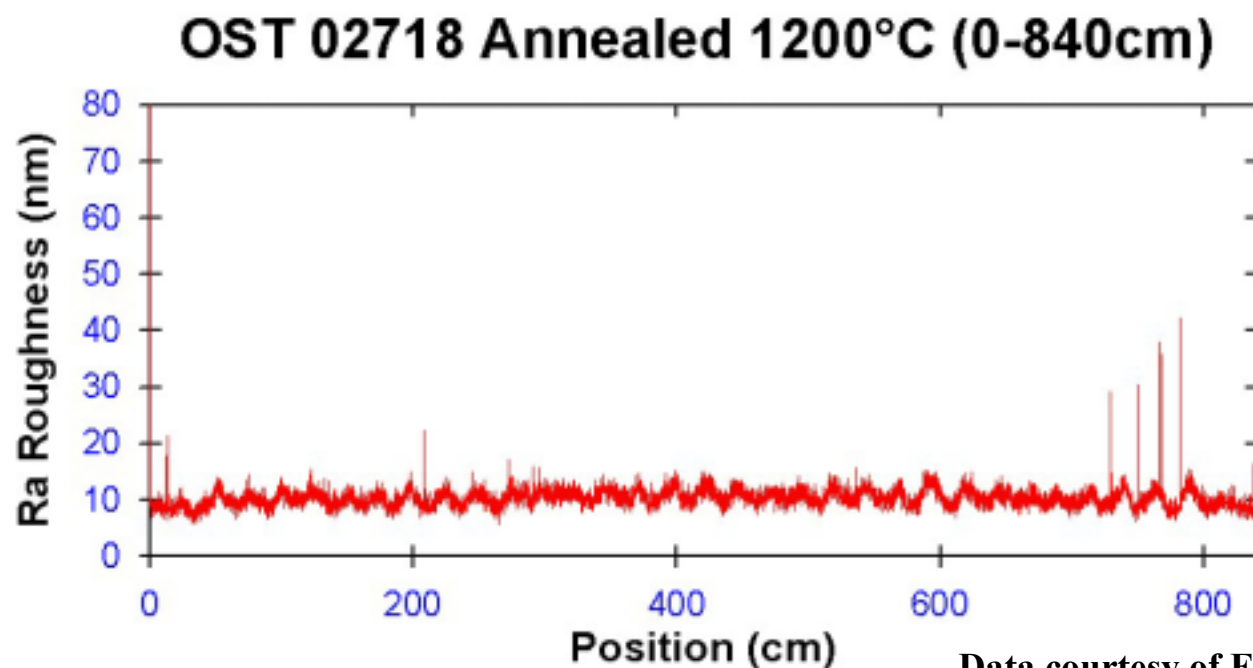
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Textured Metal: Summary Status

- 100 m lengths of continuously annealed Ni and Ni-3%W strip
- Anneal rates ~ 10 m/hr
- Surface roughness ~ 10 nm (measured by scatterometry)

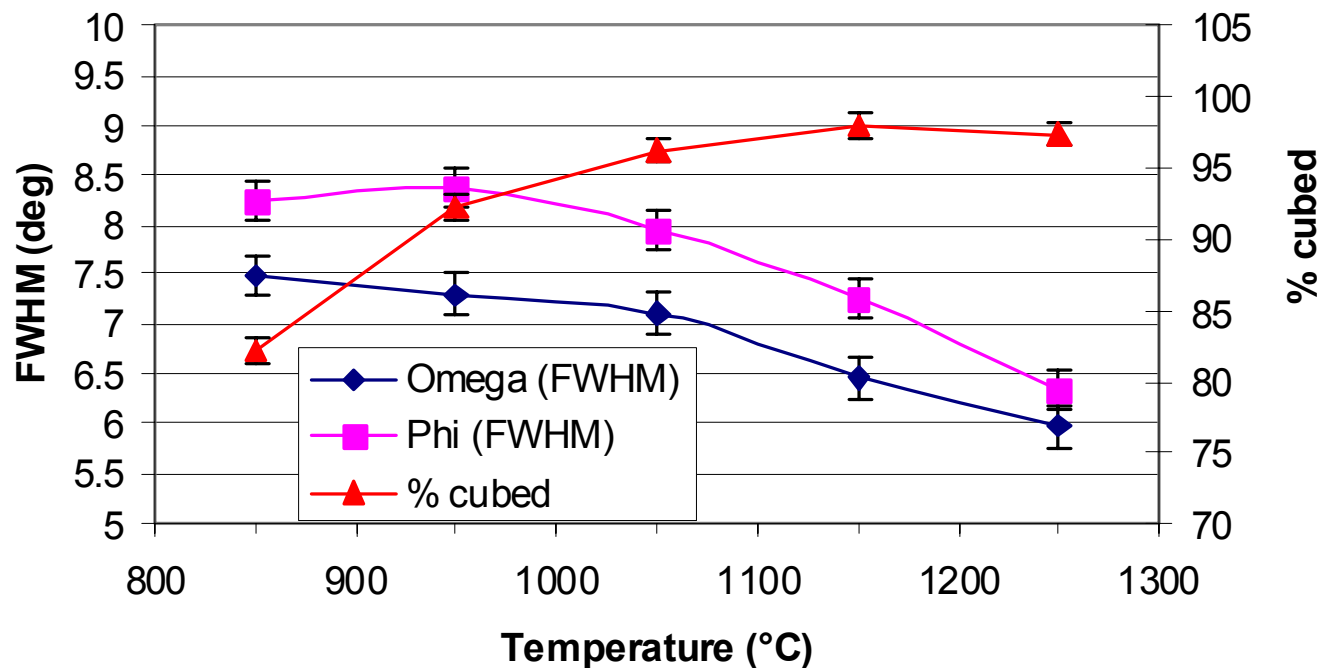


Data courtesy of Fred List, ORNL

Textured Metal: Summary Status

- Final texture developed depends on starting material, roll deformation parameters, and annealing temperature, time, and atmosphere.

X-ray Data for Oxford NiW Batch 020718

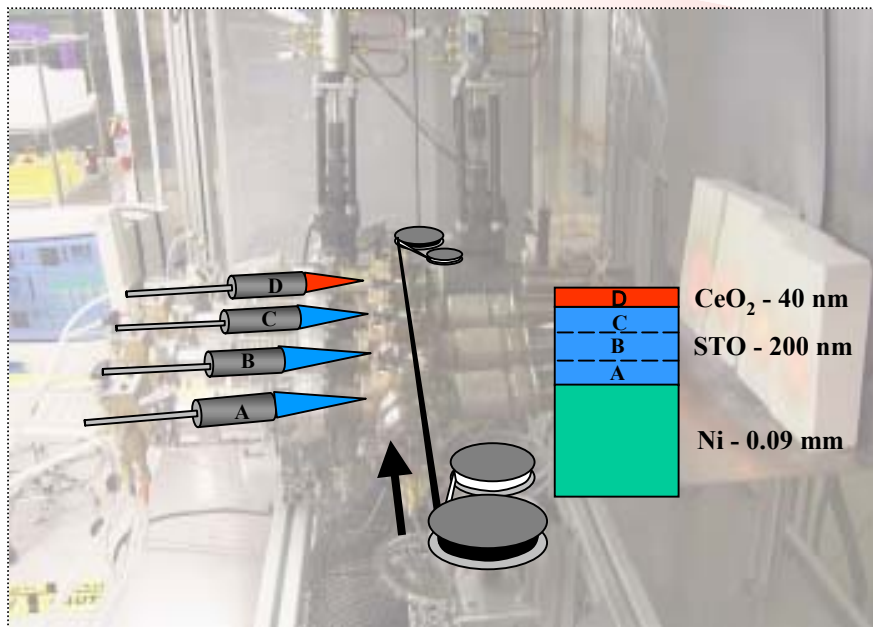


Data courtesy of Lee Heatherly, ORNL

CCVD Buffer: Architecture Versatility

• CCVD Technology:

- Atmospheric pressure flame based deposition of epitaxial buffers on reel-to-reel biaxially textured Ni or Ni-W tape.



• CCVD Advantages:

- Multi-layering flexibility
- Coating stoichiometry control and flexibility
- Non-vacuum, long length process
- Lower capital and material costs
- Non-hazardous, environmentally friendly

• Standard architecture

- 10-50 nm CeO_2 cap/
200 nm STO/BST seed

• Other materials

- Gd_2O_3 , LAO, LMO, LZO, Y_2O_3 , YSZ

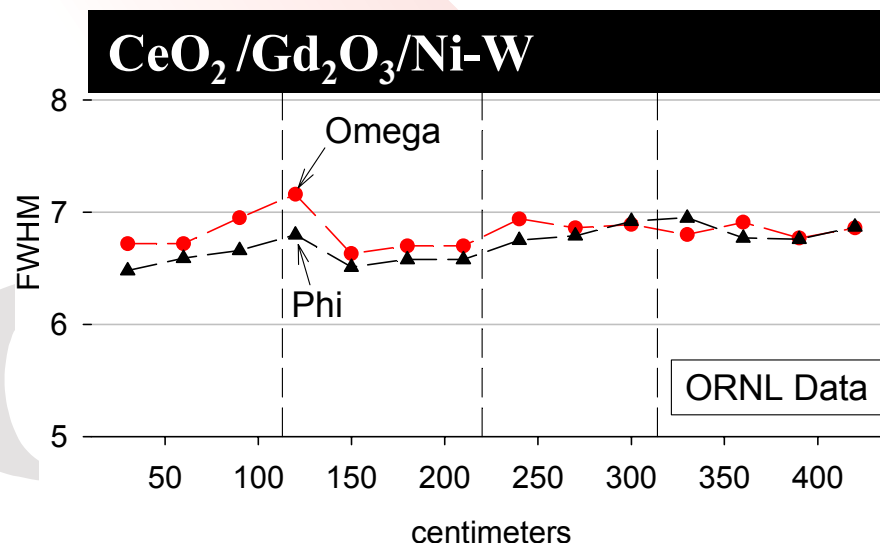
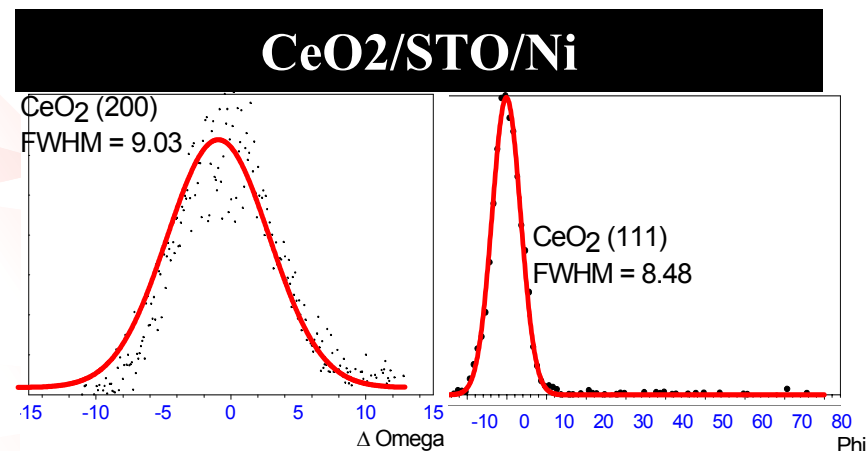
CCVD Buffer: Properties on Ni and Ni-W

• Excellent Epitaxy

- BST, STO, and CeO_2 directly on Ni
- CeO_2 and Gd_2O_3 directly on Ni-W
 - 0% in-plane misorientation
 - < 2% out-of-plane misorientation
 - Phi and omega FWHM \leq Ni
 - Uniform over meter+ lengths

• Electrical Characterization

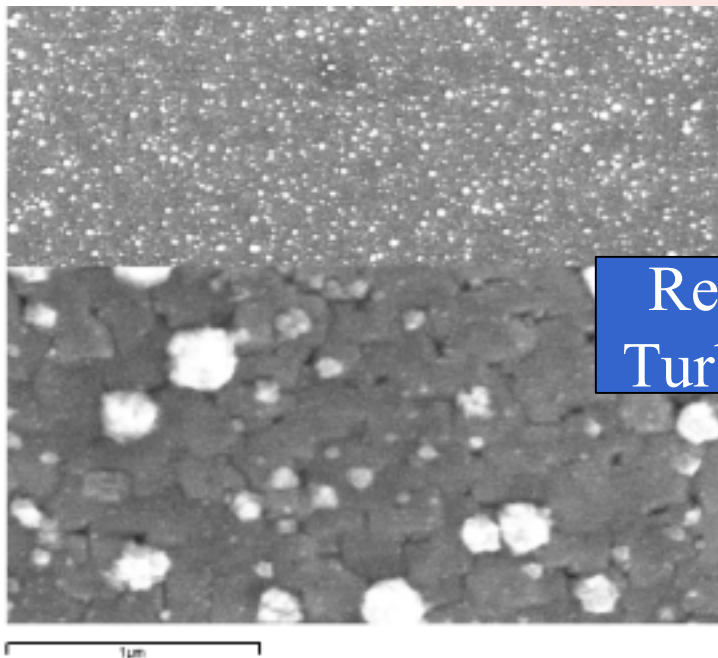
- J_c of 1.12 MA/cm² demonstrated for PLD YBCO (ORNL) on CCVD RABiTS with standard architecture
- Minimal J_c has been demonstrated with other architectures



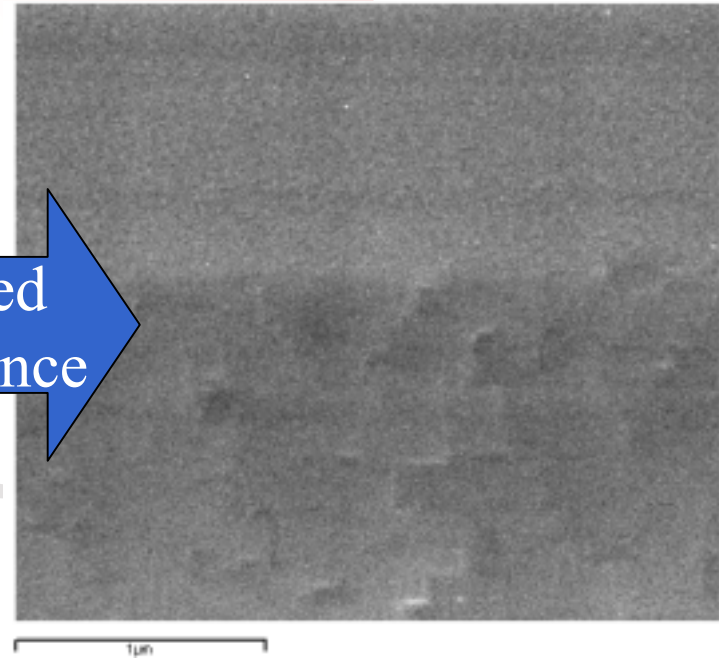
CCVD Buffer: Recent CCVD Buffer Improvements

- **Microstructure and Epitaxy Improvements**

- Reduction of gas turbulence near deposition region has reduced particle formation
 - Smoother gas flow geometries
 - Lower gas flow rates
- Smooth, dense STO microstructure
- Reduced out-of-plane misorientation
- Potential increase in subsequently deposited YBCO's current carrying capability

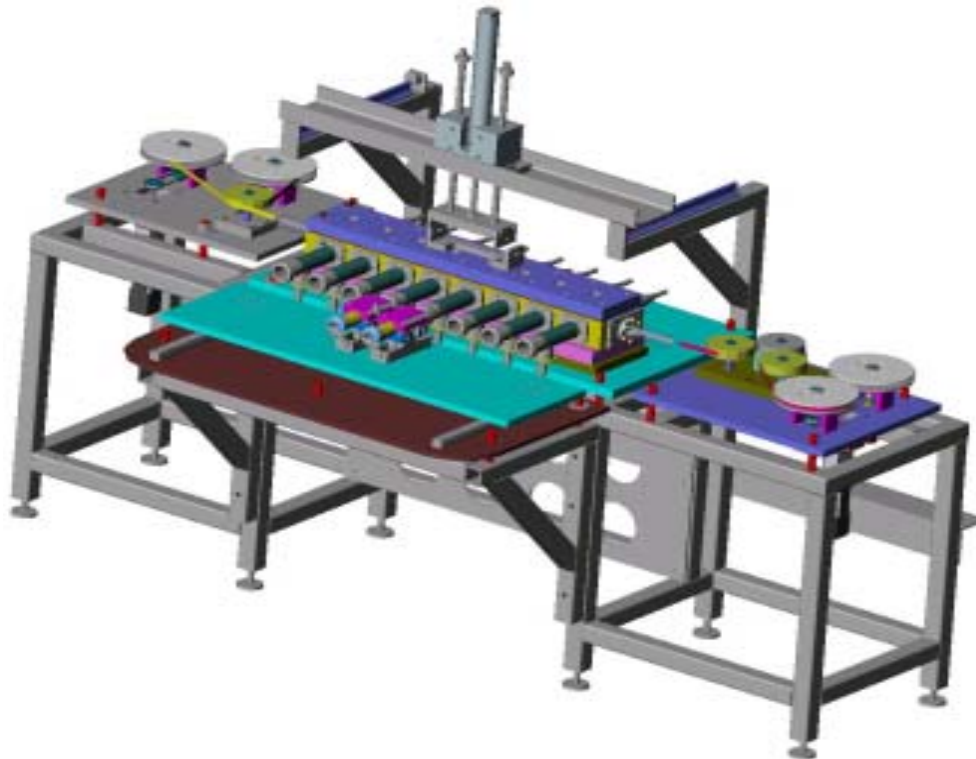


Reduced
Turbulence



CCVD Buffer: Goals for FY 2003

- Scale to 25+ meter lengths of high-quality CCVD RABiTS
- Enable critical currents of 100 amps for meter lengths (end-to-end)
- Optimize buffer architectures and properties on Ni and Ni-W
- Continue the sale of CCVD RABiTS in research quantities



CCVD YBCO: Physical Properties on RABiTS

- **Microstructure**

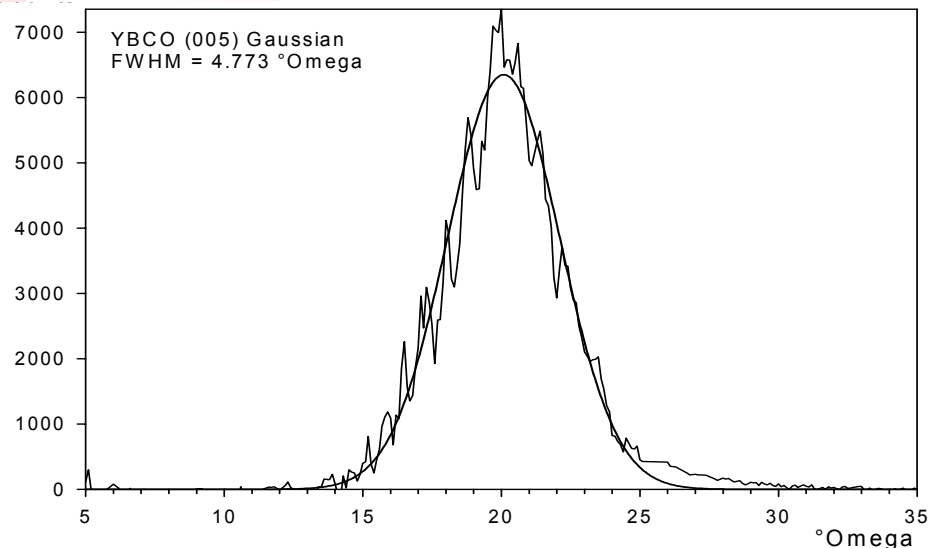
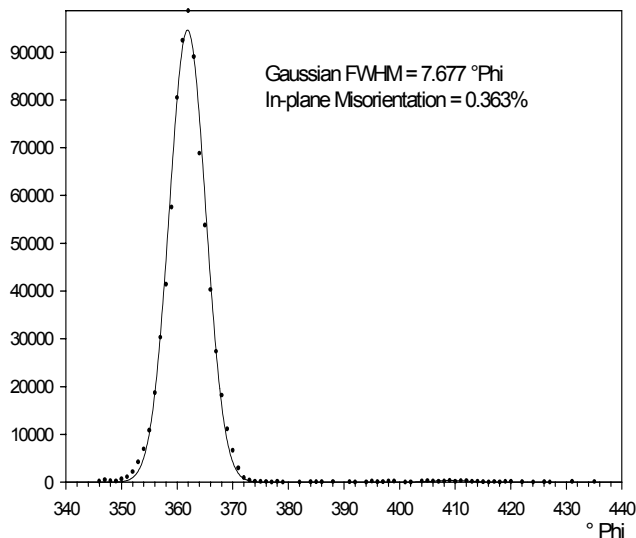
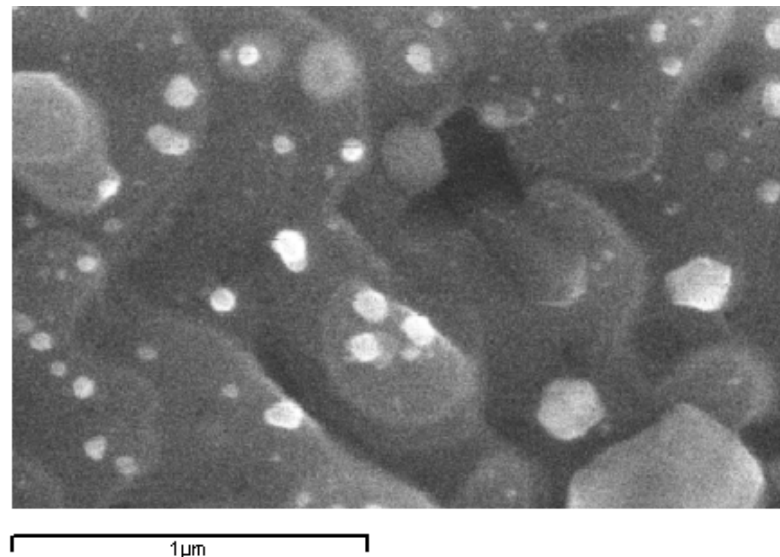
- Optimized deposition conditions
- Improved density and surface roughness
- Reduced large surface defects

- **Phase Formation**

- Reduced BaCeO_3 formation
- Reduced NiO formation

- **Epitaxy**

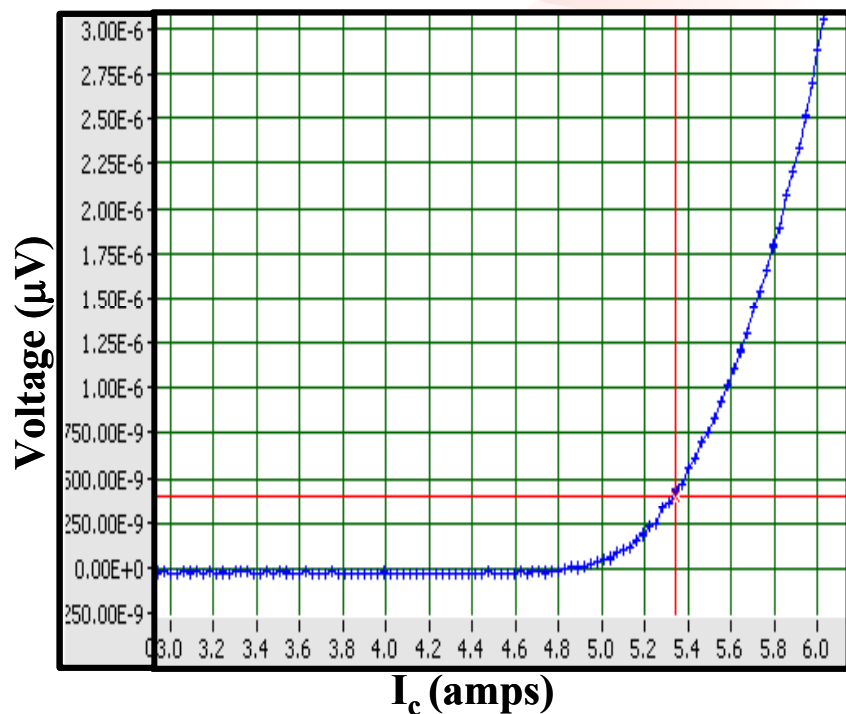
- Reduced randomly oriented YBCO
- Omega and Phi FWHM \approx RABiTS



CCVD YBCO: Electrical Properties on RABiTS

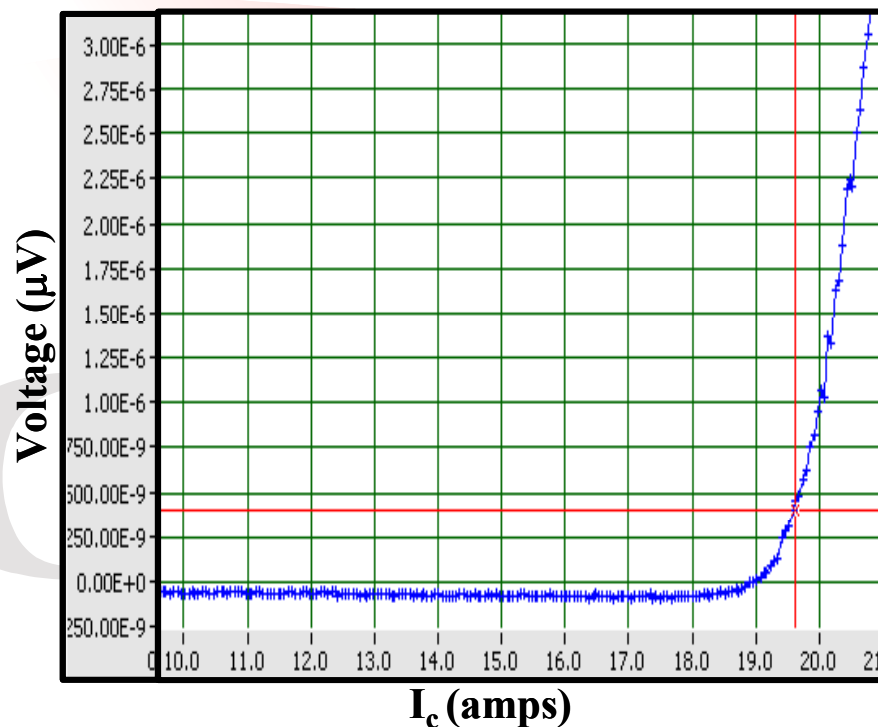
• Electrical Properties on CCVD Buffered RABiTS

- $I_c = 5.33$ A
- $J_c = \sim 0.6$ MA/cm²
- $T_c = 89$ K (<2 K transition)



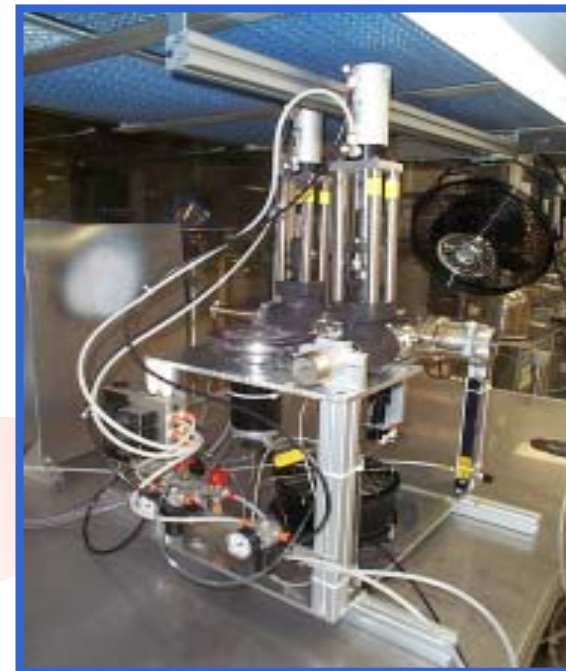
• Electrical Properties on ORNL Buffered RABiTS

- $I_c = 19.62$ A
- $J_c = \sim 1.5$ MA/cm²
- $T_c = 91$ K (<2 K transition)



CCVD YBCO: Goals for 2003

- **Scale YBCO from coupons to meter+ lengths**
 - All CCVD YBCO development has been performed in a reel to reel deposition system
- **Multiple path approach to improved CCVD YBCO on CCVD buffered RABiTS**
 - Work with CCVD buffer team to optimize buffer architectures for CCVD YBCO deposition conditions
 - Integrate process control capability that enables depositions at lower $p(\text{O}_2)$ and therefore lower temperature
- **Incorporate CCVD deposition chamber improvements developed by CCVD buffer team**
 - Increase deposition efficiency
 - Decrease surface roughness



Collaboration



- **MicroCoating Technologies**

- Optimization and scaling of RABiTS buffer deposition
- Optimization of YBCO depositions



- **Oxford Superconducting Technology**

- Optimization of Ni and Ni-W tapes
- Supplied Ni and Ni-W tapes for buffer development



- **ORNL**

- MCT and ORNL have exchanged buffer layers
- ORNL has provided MCT with Ni-W
- ORNL has deposited YBCO on CCVD RABiTS
- MCT has used the Accelerated Coated Conductor Initiative facility for reel-to-reel XRD and laser scatterometry
- MCT has purchased a commercial license for RABiTS



- **LANL**

- LANL has deposited PLD YBCO on CCVD RABiTS

- **BNL**

- BNL has deposited BaF₂ YBCO on CCVD RABiTS